



Wafer/Frame Tape Applicators

For any wafer size
including *new*
300 mm

Semiconductor Equipment Corporation's state of the art line of wafer/film tape applicators provide users with the optimal control of temperature and pressure for achieving uniform bubble-free mounting of electronic grade processing tape onto wafers and their film frames for subsequent cutting of the wafers into die. S.E.C.'s advanced systems work with virtually any film frame and cover the range of wafer diameters: the Model 3100 handles wafers up to 150 mm, the Model 3150 handles wafers up to 200 mm and the Model 300 is specifically designed for the new 300 mm wafers.

- Bubble-free tape application
- Even X-Y directional tape tensioning
- Adjustable, repeatable contact pressure
- Repeatable adhesion control
- Safe, accurate tape trimming
- Compatible with all standard film frames
- Optional non-contact platen
- Optional static eliminator





Applying tape to a 300 mm wafer using S.E.C. Model 300 Wafer/Film Frame Tape Applicator.

Bubble-free tape application

With vacuum holding the wafer in position, a captive roller travels from the front of the applicator along fixed guide rails over the wafer and film frame in a manner which eliminates any chance of entrapped pockets of air being formed between the tape and wafer which can create areas of low or no adhesion.

Even X-Y directional tape tensioning

A preset tensioning frame stretches and holds the tape uniformly in all directions while the tape is rolled into contact against the wafer and film frame.

Adjustable, repeatable contact pressure

The captive roller is coupled with an adjustable spring loaded platen to deliver the repeatable mounting pressure that is so important for achieving consistent wafer application.

Repeatable adhesion control

A digital closed loop temperature controller regulates the mounting temperature to ensure repeatable adhesion.

Safe accurate tape trimming

A built-in rotary cutter offers exceptional operating life and quickly, safely and accurately trims the tape away from the tension frame. The blade automatically retracts safely when not in use.

Compatible with all standard film frames

Universal design allows any standard frame to be accurately positioned against locating pins. Magnets hold the frame in place.

Optional non-contact platen

When it is not desirable for the face of the wafer to come into contact with the platen, an optional non-contact platen is available. With this option, the wafer is held in position by vacuum along a narrow ridge around the wafer's perimeter. A pressure backup supports the wafer during the tape application. The majority of the wafer remains untouched.

Optional static eliminator

Located in the tape path, this device prevents static electricity from building up in the tape.

Specifications

	MODEL 3100	MODEL 3150	MODEL 300
Weight	75 lbs.	90 lbs.	120 lbs.
Height	8"	8"	10"
Length	28"	32"	40"
Width	14"	17"	25"
Shipping Wt.	80 lbs	100 lbs.	180 lbs.
Voltage: 110 or 220 VAC-50/60 Hz • Vacuum: 25" H ₂ • Current 3 A			

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